

Versatile, easy-to-use blade optimized for performance,
power and cooling



IBM BladeCenter HS22



Highlights

- ***Improve service with unparalleled RAS features and innovative management***
- ***Reduce cost through increased performance, utilization and efficiency***
- ***Manage growth and reduce risk on a BladeCenter platform with proven stability***

Designed for versatility

The IBM® BladeCenter® HS22 offers flexible options to support a broad range of workloads, including virtualization and enterprise applications. Along with intuitive UEFI-based tools, the HS22 can be customized and deployed quickly while best-in-class reliability features help keep you up and running. Mix and match the HS22 with the industry's most diverse set of chassis and blades and that go beyond x86.

Built for performance

The HS22 provides outstanding performance with support for the latest Intel® Xeon® processors, high-speed I/O, and support for high memory capacity and fast memory throughput. The HS22 can run applications up to twice as fast compared to previous generation blades. In fact, you can run many applications faster than even competitor four-socket blades.

Optimized for power, cooling efficiency

The HS22 features an innovative mechanical design optimized for cooling capability to help keep the blade running smoothly even under demanding conditions. Combined with low-voltage components, the industry's most energy-efficient chassis, and robust power management tools, the HS22 helps control power consumption and maximize efficiency.

IBM BladeCenter HS22 at a glance

Form factor	Single-wide (30 mm)
Processor (max)	Choice of two Intel Xeon 5500 series processors, up to 2.93 GHz
Number of processors (std/max)	1/2
Cache (max)	8 MB (quad-core)
Memory (max)	Twelve DDR-3 VLP DIMM slots (up to 96 GB of total memory capacity and memory speeds up to 1333 MHz)
Expansion slots	1 CIOv slot (standard PCI-Express daughter card) and 1 CFFh slot (high-speed PCI-Express daughter card) for a total of 8 ports of I/O to each blade, including 4 ports of high-speed I/O
Disk bays (total/hot-swap)	2 hot-swap bays supporting SAS HDDs or solid-state drives
Maximum internal storage^{1,2}	Up to 600 GB total internal storage
Network interface	Broadcom 5709S onboard NIC with dual Gigabit Ethernet ports with TOE
Hot-swap components	Internal storage bays
RAID support	RAID-0, -1 and -1E (optional RAID-5 with battery-backed cache)
Systems management	Unified Extensible Firmware Interface (UEFI), IBM Integrated Management Module (IMM), Predictive Failure Analysis®, optional embedded hypervisor for virtualization, IBM Systems Director Active Energy Manager™, light path diagnostics, IBM Systems Director and IBM ServerGuide™
Operating systems supported	Microsoft® Windows®, Linux®, Sun Solaris and VMware
Limited warranty³	3-year customer replaceable unit and onsite and offsite limited warranty

For more information

World Wide Web

U.S.	ibm.com/bladecenter
Canada	ibm.com/systems/ca/en/servers/bladecenter/

¹ Maximum internal hard disk and memory capacities may require the replacement of any standard hard drives and/or memory and the population of all hard disk bays and memory slots with the largest capacity supported drives available. When referring to variable speed CD-ROMs, CD-Rs, CD-RWs and DVDs, actual playback speed will vary and is often less than the maximum possible.

² GB and TB = 1,000,000,000 and 1,000,000,000,000 bytes, respectively, when referring to storage capacity. Accessible capacity is less.

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